

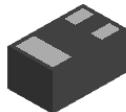
Features

- Epitaxial Die Construction
- Complementary NPN Type Available (BC847BLP)
- Ultra-Small Leadless Surface Mount Package
- "Lead Free", RoHS Compliant (Note 1)**
- Halogen and Antimony Free "Green" Device (Note 2)**
- Qualified to AEC-Q101 Standards for High Reliability

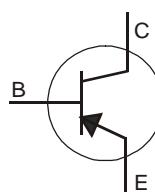
Mechanical Data

- Case: DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0009 grams

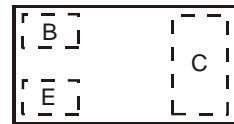
DFN1006-3



Bottom View



Device Symbol


 Top View
 Pin-Out

Ordering Information (Note 3)

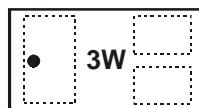
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BC857BLP-7	3W	7	8mm	3,000
BC857BLP-7B	3W	7	8mm	10,000

Notes:

1. No purposefully added lead.
2. Halogen and Antimony Free. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>.
3. For packaging details, go to our website at <http://www.diodes.com>.

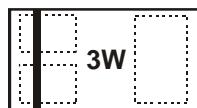
Marking Information

BC857BLP-7



Top View
 Dot Denotes
 Collector Side

BC857BLP-7B



Top View
 Bar Denotes Base
 and Emitter Side

3W = Product Type Marking Code

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-50	V
Collector-Emitter Voltage	V_{CEO}	-45	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-100	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4) @ $T_A = 25^\circ\text{C}$	P_D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 4) @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$	500	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic (Note 5)	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-50	—	—	V	$I_C = 10\mu\text{A}, I_B = 0$
Collector-Emitter Breakdown Voltage	BV_{CEO}	-45	—	—	V	$I_C = 10\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	-5	—	—	V	$I_E = 1\mu\text{A}, I_C = 0$
DC Current Gain	h_{FE}	220	260	475	—	$V_{CE} = -5.0\text{V}, I_C = -2.0\text{mA}$
Collector-Emitter Saturation Voltage	$V_{CE(\text{sat})}$	—	-90 -250	-300 -650	mV	$I_C = -10\text{mA}, I_B = -0.5\text{mA}$ $I_C = -100\text{mA}, I_B = -5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(\text{sat})}$	—	-700 -850	—	mV	$I_C = -10\text{mA}, I_B = -0.5\text{mA}$ $I_C = -100\text{mA}, I_B = -5.0\text{mA}$
Base-Emitter Voltage	$V_{BE(\text{on})}$	-600 —	-670 -710	-750 -820	mV	$V_{CE} = -5.0\text{V}, I_C = -2.0\text{mA}$ $V_{CE} = -5.0\text{V}, I_C = -10\text{mA}$
Collector-Cutoff Current	I_{CBO}	—	—	-15 -4.0	nA μA	$V_{CB} = -30\text{V}$ $V_{CB} = -30\text{V}, T_A = 150^\circ\text{C}$
Gain Bandwidth Product	f_T	100	—	—	MHz	$V_{CE} = -5.0\text{V}, I_C = -10\text{mA}, f = 100\text{MHz}$
Collector-Base Capacitance	C_{CBO}	—	3.0	—	pF	$V_{CB} = -10\text{V}, f = 1.0\text{MHz}$

Notes:

4. Device mounted on FR-4 PCB, Diodes Inc. suggested pad layout document can be found on our website at <http://www.diodes.com>.
5. Short duration pulse test used to minimize self-heating effect.

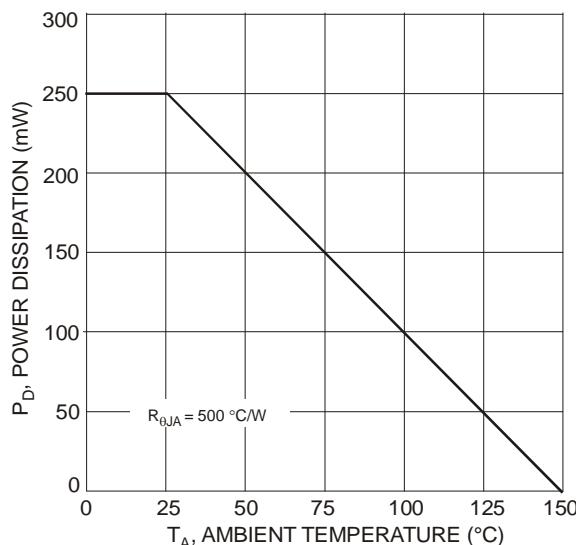


Fig. 1 Power Dissipation
vs. Ambient Temperature (Note 4)

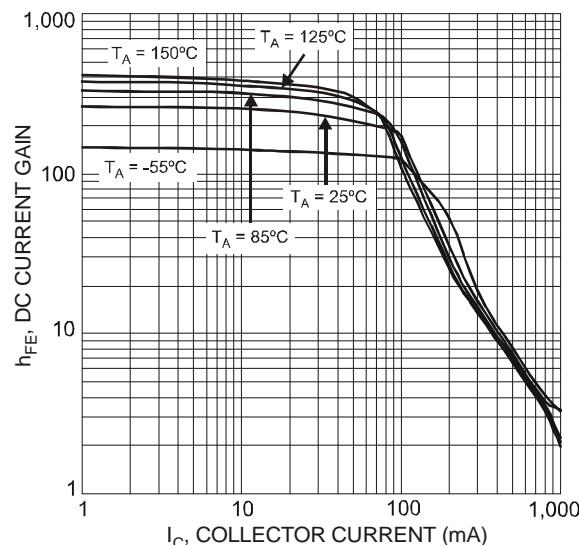


Fig. 2 Typical DC Current Gain vs. Collector Current

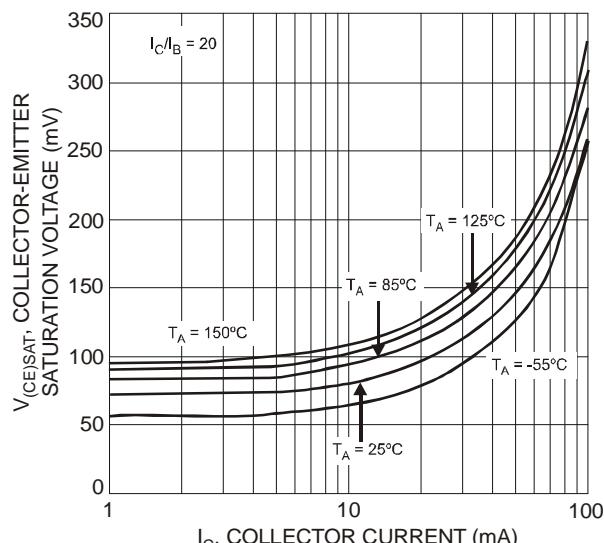


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

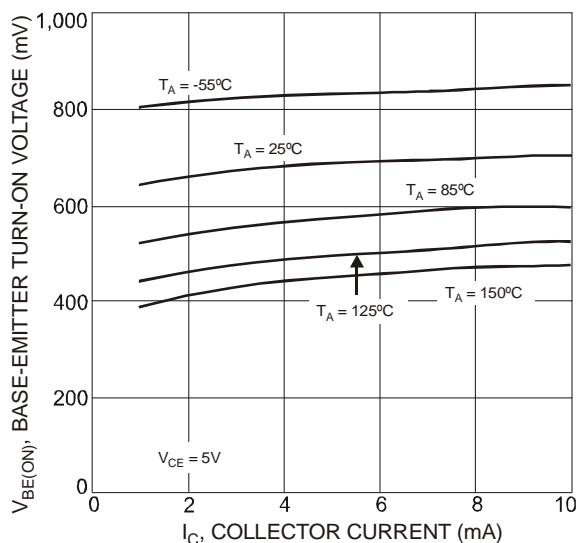


Fig. 4 Typical Base-Emitter Turn-On Voltage vs. Collector Current

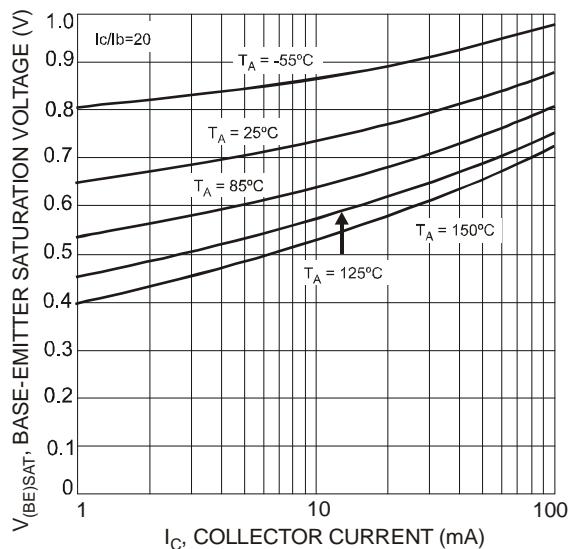
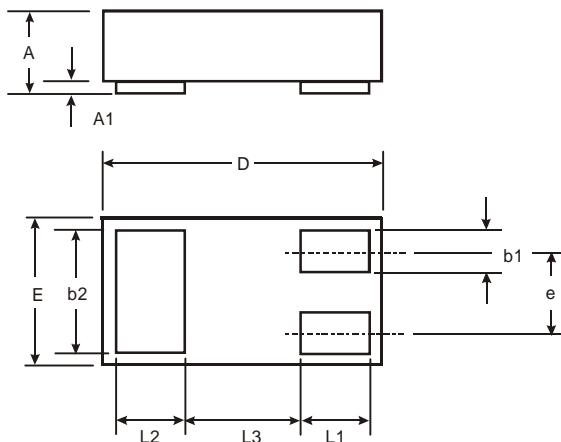


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

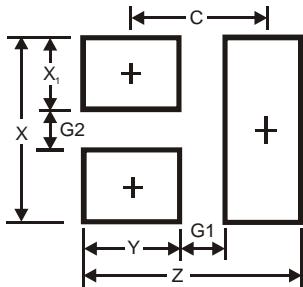
Package Outline Dimensions



DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40

All Dimensions in mm

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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